These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
- These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ3
- ESD precautions shall be observed.
- These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ1
- These assemblies are ESD sensitive.
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